

30 A - 600 V - fast IGBT

Features

- Very low on-voltage drop ($V_{CE(sat)}$)
- High current capability
- Minimum power losses at 5 kHz in hard switching
- Optimized performance for medium operating frequencies.

Application

- Medium frequency motor control

Description

This IGBT utilizes the advanced PowerMESH™ process resulting in an excellent trade-off between switching performance and low on-state behavior.

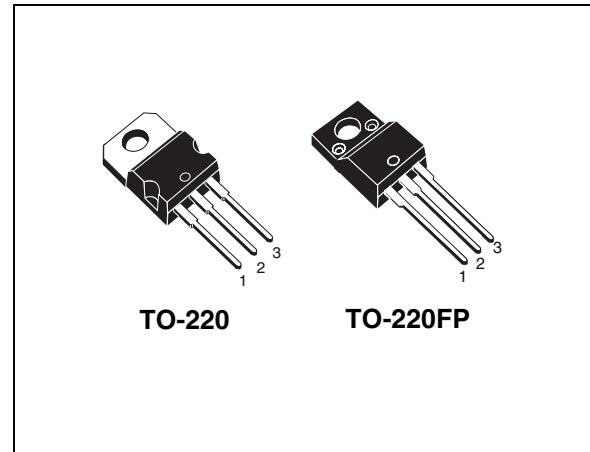


Figure 1. Internal schematic diagram

Table 1. Device summary

Part number	Marking	Package	Packaging
STGF30NC60S	GF30NC60S	TO-220FP	Tube
STGP30NC60S	GP30NC60S	TO-220	Tube

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220	TO-220FP	
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	600		V
$I_C^{(1)}$	Continuous collector current at $T_C = 25^\circ\text{C}$	55	22	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100^\circ\text{C}$	35	11	A
$I_{CL}^{(2)}$	Turn-off latching current	150		A
$I_{CP}^{(3)}$	Pulsed collector current	150		A
V_{GE}	Gate-emitter voltage	± 20		V
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t=1\text{ s}; T_C=25^\circ\text{C}$)		2500	V
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	175	40	W
T_j	Operating junction temperature	– 55 to 150		$^\circ\text{C}$

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(\max)}, I_C(T_C))}$$

2. $V_{clamp} = 80\% \cdot (V_{CES})$, $T_j = 150^\circ\text{C}$, $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$
3. Pulse width limited by max. junction temperature allowed

Table 3. Thermal data

Symbol	Parameter	Value		Unit
		TO-220	TO-220FP	
$R_{thj-case}$	Thermal resistance junction-case	0.7	3.1	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5		$^\circ\text{C/W}$

2 Electrical characteristics

($T_J = 25^\circ\text{C}$ unless otherwise specified)

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ($V_{GE} = 0$)	$I_C = 1 \text{ mA}$	600			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_C = 20 \text{ A}$ $V_{GE} = 15 \text{ V}, I_C = 20 \text{ A}, T_J = 150^\circ\text{C}$		1.5 1.4	1.9	V V
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 250 \mu\text{A}$	3.75		5.75	V
I_{CES}	Collector cut-off current ($V_{GE} = 0$)	$V_{CE} = 600 \text{ V}$ $V_{CE} = 600 \text{ V}, T_J = 150^\circ\text{C}$			150 1	μA mA
I_{GES}	Gate-emitter cut-off current ($V_{CE} = 0$)	$V_{GE} = \pm 20 \text{ V}$			± 100	nA
$g_{fs}^{(1)}$	Forward transconductance	$V_{CE} = 15 \text{ V}, I_C = 20 \text{ A}$		10		S

1. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance			2200		pF
C_{oes}	Output capacitance		-	185	-	pF
C_{res}	Reverse transfer capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0$		48.5		pF
Q_g	Total gate charge			96		nC
Q_{ge}	Gate-emitter charge	$V_{CE} = 480 \text{ V}, I_C = 20 \text{ A},$ $V_{GE} = 15 \text{ V}$	-	14	-	nC
Q_{gc}	Gate-collector charge	Figure 18		44.5		nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480 \text{ V}$, $I_C = 20 \text{ A}$ $R_G = 10 \Omega$, $V_{GE} = 15 \text{ V}$ <i>Figure 17</i>	-	21.5 8.5 2280	-	ns ns A/ μs
$t_{d(on)}$ t_r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480 \text{ V}$, $I_C = 20 \text{ A}$ $R_G = 10 \Omega$, $V_{GE} = 15 \text{ V}$, $T_J = 125^\circ\text{C}$ <i>Figure 17</i>	-	20.5 9.5 2150	-	ns ns A/ μs
$t_r(V_{off})$ $t_d(off)$ t_f	Off voltage rise time Turn-off delay time Current fall time	$V_{cc} = 480 \text{ V}$, $I_C = 20 \text{ A}$, $R_{GE} = 10 \Omega$, $V_{GE} = 15 \text{ V}$ <i>Figure 17</i>	-	85 180 200	-	ns ns ns
$t_r(V_{off})$ $t_d(off)$ t_f	Off voltage rise time Turn-off delay time Current fall time	$V_{cc} = 480 \text{ V}$, $I_C = 20 \text{ A}$, $R_{GE} = 10 \Omega$, $V_{GE} = 15 \text{ V}$ $T_J = 125^\circ\text{C}$ <i>Figure 17</i>	-	155 260 295	-	ns ns ns

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
E_{on} $E_{off}^{(1)}$ E_{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 \text{ V}$, $I_C = 20 \text{ A}$ $R_G = 10 \Omega$, $V_{GE} = 15 \text{ V}$, <i>Figure 17</i>	-	300 1275 1575	-	μJ μJ μJ
E_{on} $E_{off}^{(1)}$ E_{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 \text{ V}$, $I_C = 20 \text{ A}$ $R_G = 10 \Omega$, $V_{GE} = 15 \text{ V}$, $T_J = 125^\circ\text{C}$ <i>Figure 17</i>	-	430 1965 2395	-	μJ μJ μJ

1. Turn-off losses include also the tail of the collector current.

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

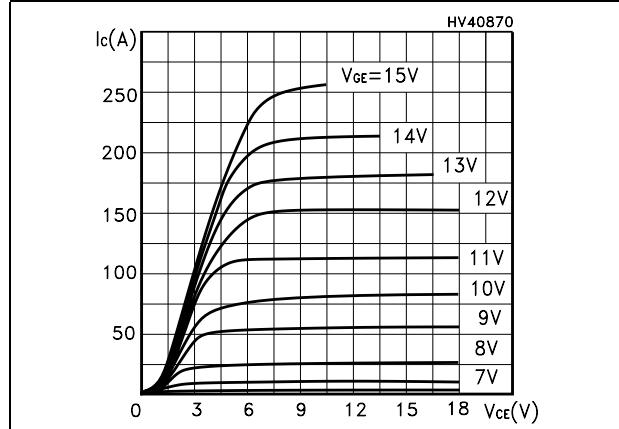


Figure 3. Transfer characteristics

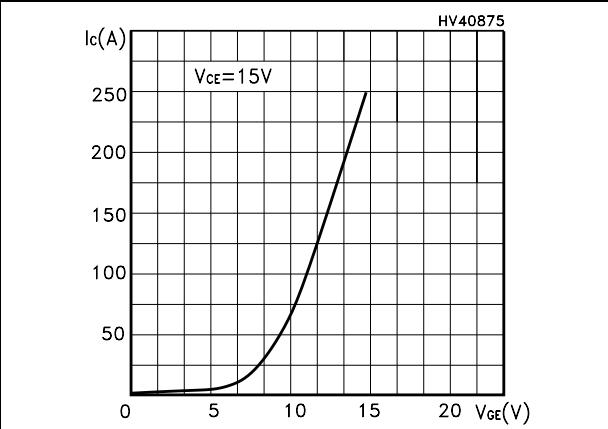


Figure 4. Transconductance

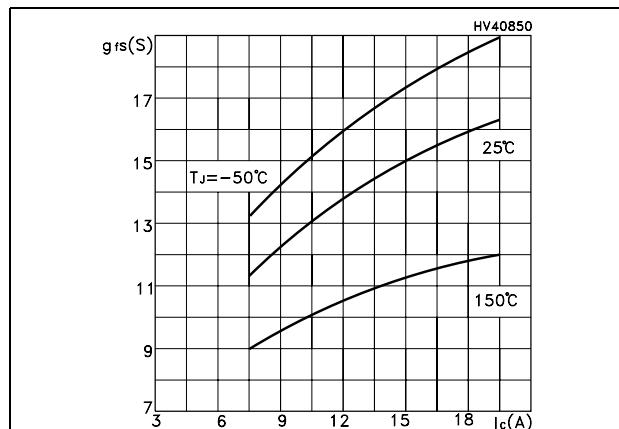


Figure 5. Collector-emitter on voltage vs temperature

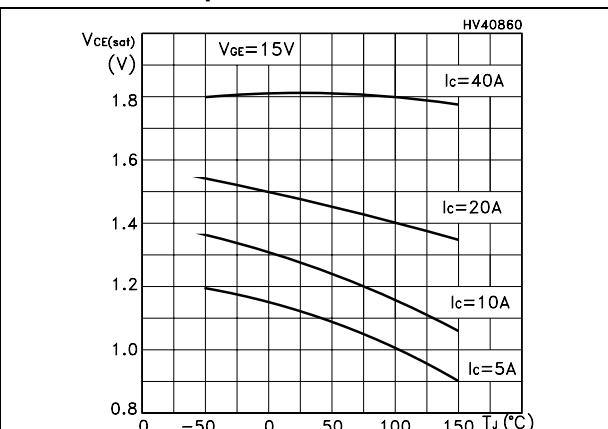


Figure 6. Gate charge vs gate-source voltage

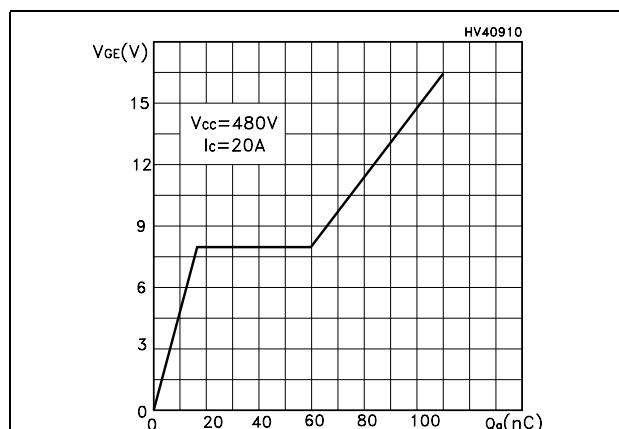


Figure 7. Capacitance variations

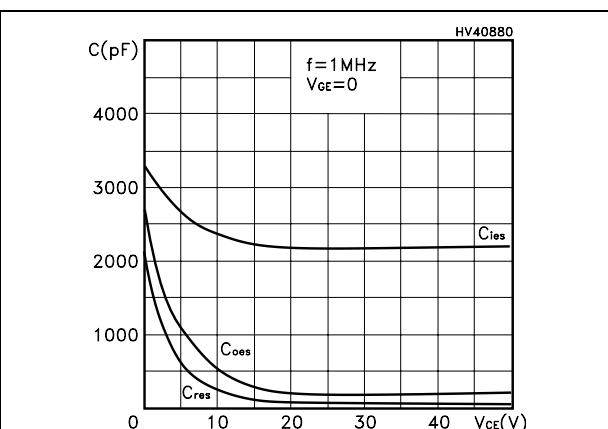


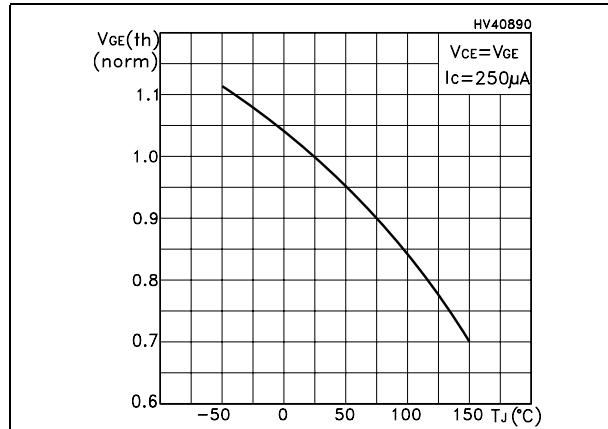
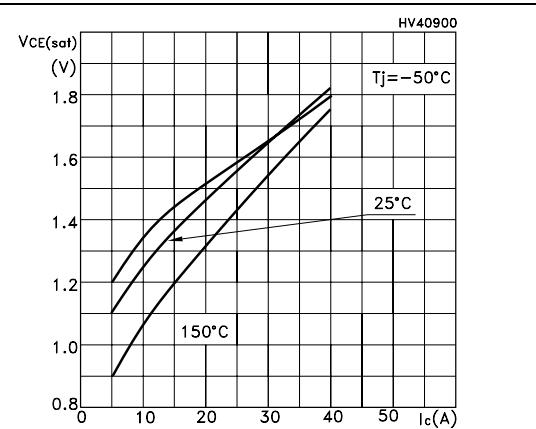
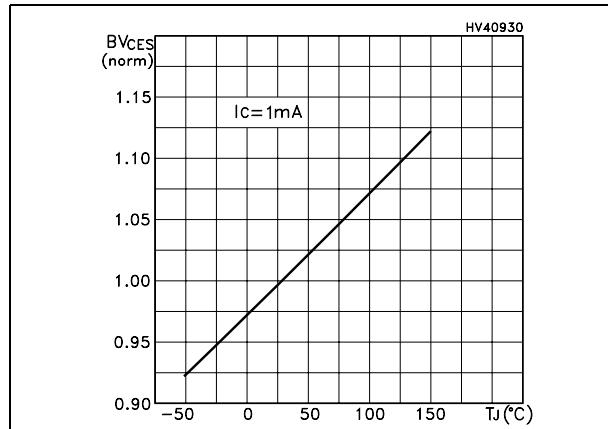
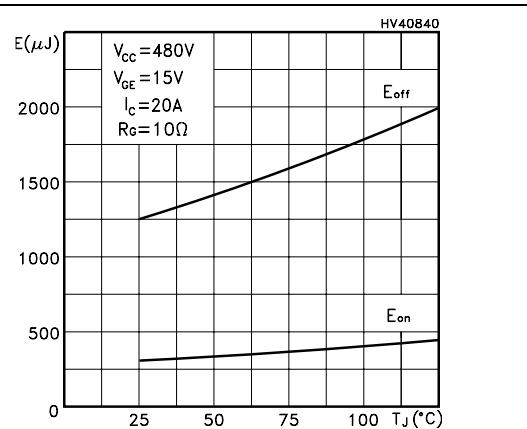
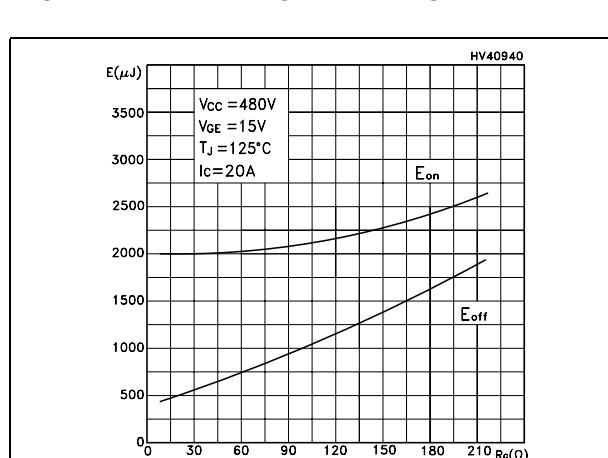
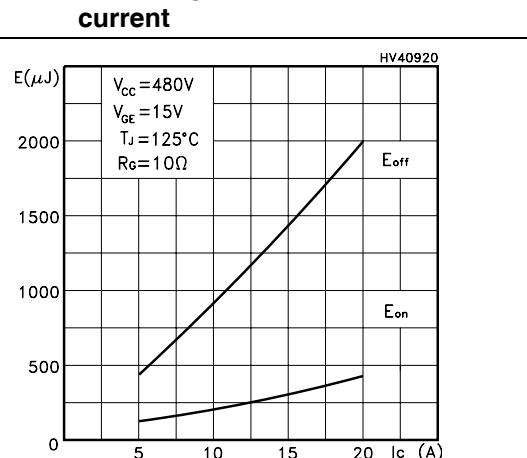
Figure 8. Normalized gate threshold voltage vs temperature**Figure 9. Collector-emitter on voltage vs collector current****Figure 10. Normalized breakdown voltage vs temperature****Figure 11. Switching losses vs temperature****Figure 12. Switching losses vs gate resistance****Figure 13. Switching losses vs collector current**

Figure 14. Thermal Impedance

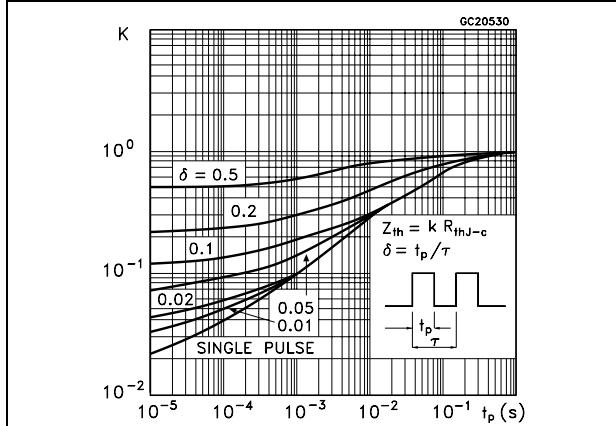


Figure 15. Turn-off SOA

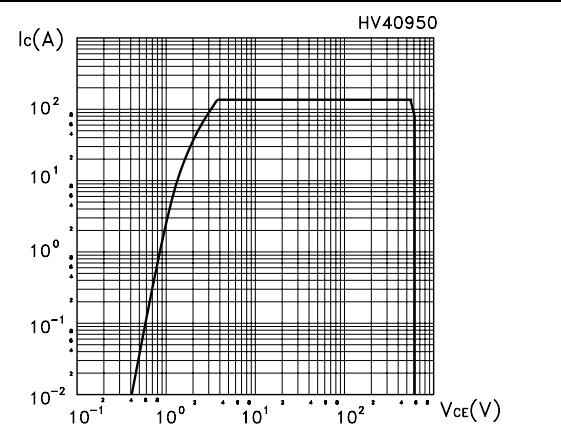
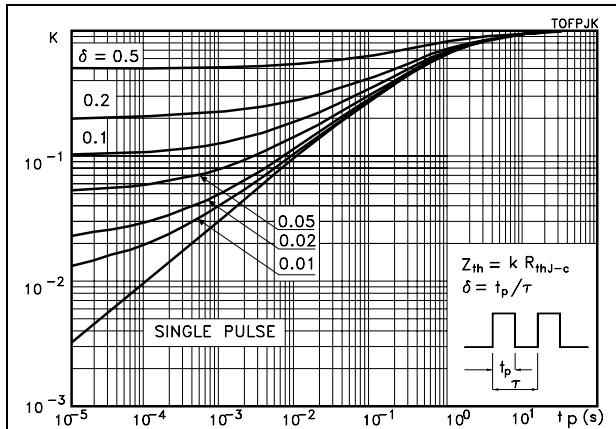


Figure 16. Thermal Impedance for TO-220FP



3 Test circuits

Figure 17. Test circuit for inductive load switching

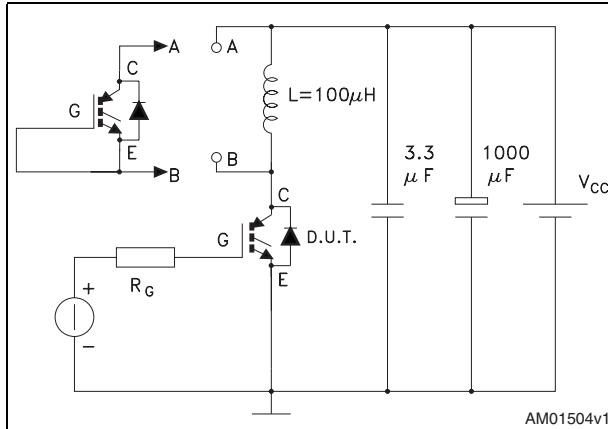


Figure 18. Gate charge test circuit

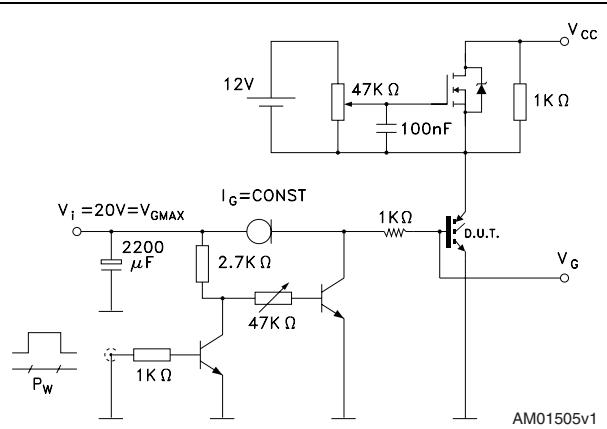
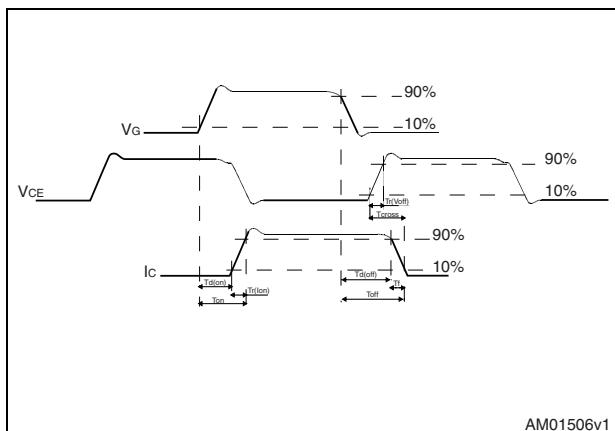


Figure 19. Switching waveforms

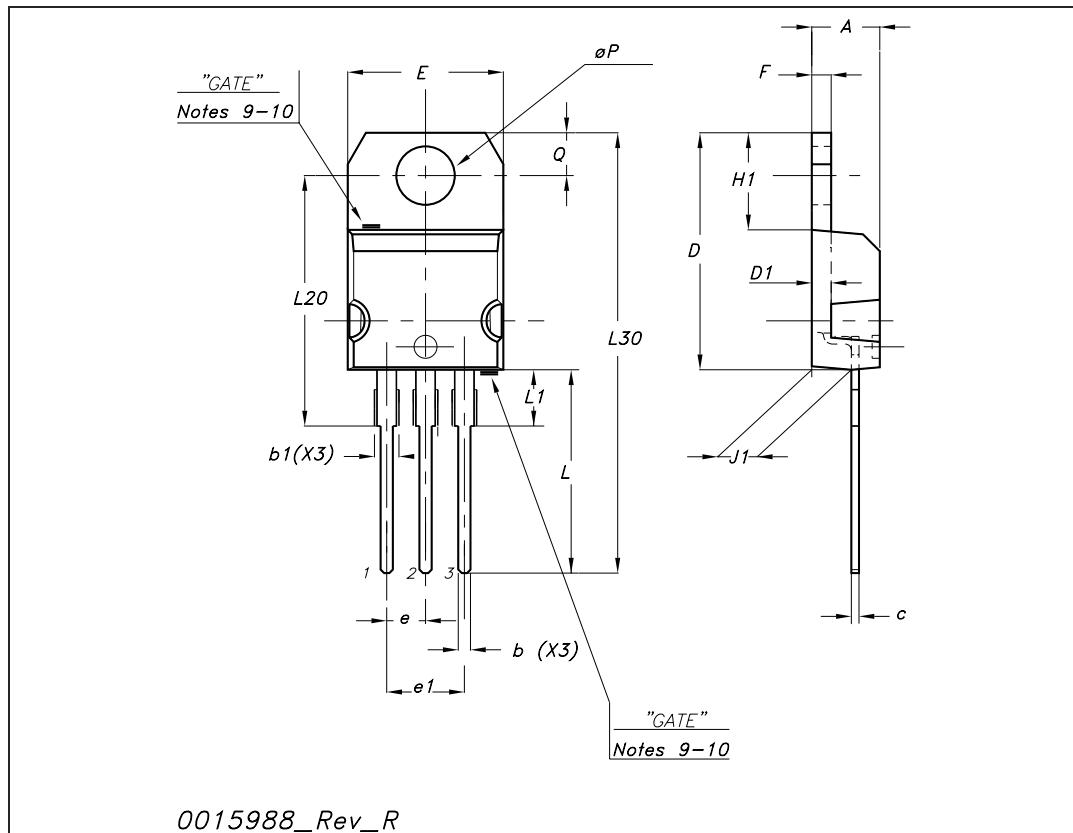


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

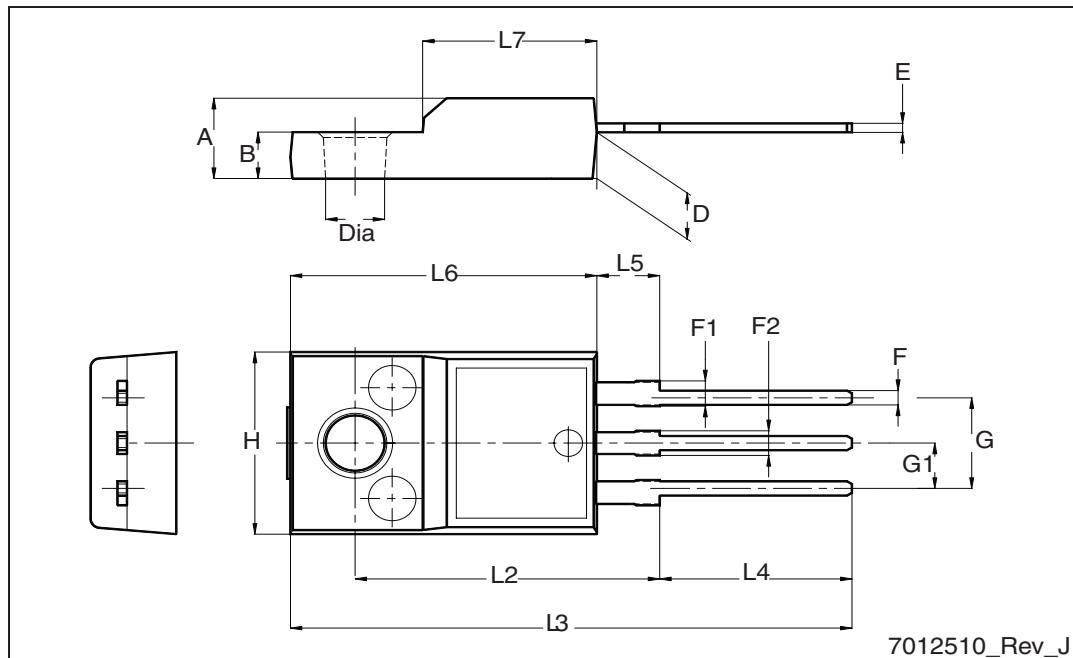
TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
$\emptyset P$	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.5
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2



5 Revision history

Table 8. Document revision history

Date	Revision	Changes
02-Jul-2007	1	Initial release
20-Nov-2007	2	Document status promoted from preliminary data to datasheet
04-May-2009	3	Added new package, mechanical data: TO-220FP

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